

TOREX SEMICONDUCTOR LTD.
Quality Assurance Dept.

Composition Table

Product(Pb-free): XC6415xxxx7R-G
Typical Mass: 1.8 mg

Part name	Weight(mg)	Material name	Ratio(ppm)	CAS number
Silicon chip	0.399	Silicon	221600	7440-21-3
	-	Arsenic	<1	7440-38-2
Lead pad	0.386	Nickel	214400	7440-02-0
	0.003	Gold	1700	7440-57-5
Die attach	0.018	Epoxy Resin	9700	—
	0.011	Acrylic Resin	5800	—
Bonding wire	0.071	Gold	39400	7440-57-5
Resin	0.799	Silica	443900	60676-86-0
	0.046	Epoxy Resin	25400	—
	0.041	Phenol Resin	22800	—
	0.027	Metal hydroxide	15200	—

* The component composition is based on the information provided by raw material vender.

* The mass of the IC and its fractions could be different due to the manufacturing conditions of materials.

* Any indication "-" in CAS number means "confidential."